

# STENCILQUIK TECHNICAL DATA SHEET

### **4 MILS STENCILQUIK**



### **General Description**

StencilQuik stencils are made from two layers of clear amber polyimide film with an adhesive backing. It is coated with an aggressive permanent acrylic adhesive and backed with a 50# Kraft release liner. The Stencil-Quik stencils are pre-scored to allow for easy removal of the release liner.

#### Uses

Intended for use as a "remain-in-place" stencil for the application of solder paste or fux on printed circuit boards. The stencil material is designed to withstand high temperatures and harsh chemicals. W ithstands through-hole and surface mount circuit board processes. This high-performance material is designed for applications requiring excellent solvent and heat resistance. StencilQuik stencils are designed with a permanent adhesive and they are not designed to be removed after being applied.

### Features

Excellent chemical, and heat resistance. The StencilQuik stencil is dimensionally stable (no shrinkage) with a high-performance adhesive. StencilQuik stencils have insulative properties in the material and adhesive. The minimum break through voltage (the voltage that will not pass through the polyimide) is 5000 volts. The voltage that will pass through the polyimide material is approximately 7000 volts.

### **Physical Properties**

Description	Material	Convention Units	S.I. Units
Thickness	Polyimide Adhesive Liner (50#) Total (Results in a solder print thic	2.0 mils 2.0 mils 3.0 mils 7.0 mils kness of 0.008")	102 microns 102 microns 75 microns 279 microns
Adhesive Performance	Stainless Steel Fiberglass Phenolic Nylon (Adhesive performance afte	72.00 oz/in 28.98 oz/in 29.97 oz/in 40.55 oz/in r a 72 hour dwell)	790.00 N/m 317.32 N/m 328.17 N/m 444.01 N/m
Service Temperatures	1-40 minutes 2-4 minutes 1-9 seconds 1-3 seconds	572°F 617°F 842°F 1000°F	300°C 325°C 450°C 538°C



Application Temp.	Minimum	50°F	10°C
Chemical Resistance	consist of five cycles of 10 m	room temperature after 24 ho inute immersions in the specie ery periods. Cotton swab rub No effect No effect No effect Spirits No effect No effect No effect No effect No effect No effect No effect	fied chemical reagent
Storage Stability	Product should be stored at humidity to ensure optimal	70 degrees F (21 degrees C) a performance.	and 40 – 50% relative
Shelf Life	2 Years at the proper storag	e conditions.	

## **8 MILS STENCILQUIK**

### **General Description**

StencilQuik stencils are made from two layers of cl ear amber polyimide film with an adhesive backing. It is coated with an aggressive permanent acrylic adhesive and backed with a 50# Kraft release liner. The StencilQuik stencils are pre-scored to allow for easy removal of the release liner.

#### Uses

Intended for use as a "remain-in-place" stencil for the application of solder paste or flux on printed circuit boards. The stencil material is designed to withstand high temperatures and harsh chemicals. W ithstands through-hole and surface mount circuit board processes .This high-performance material is designed for applications requiring excellent solvent and heat resistance. StencilQuik stencils are designed with a permanent adhesive and they are not designed to be removed after being applied.

### Features

Excellent chemical, and heat resistance. The StencilQuik stencil is dimensionally stable (no shrinkage) with a high-performance adhesive. StencilQuik stencils have insulative properties in the material and adhesive. The minimum break through voltage (the voltage that wiln ot pass through the polyimide) is 5000 volts. The voltage that will pass through thep olyimide material is approximately 7000 volts.

### **Physical Properties**

Description	Material	Convention Units	S.I. Units
Thickness	Polyimide Adhesive Liner (50#) Total	4.0 mils 4.0 mils 3.0 mils 11.0 mils	102 microns 102 microns 75 microns 279 microns
	(Results in a solder print thickness of 0.008")		



Adhesive	Stainless Steel	72.00 o	z/in	790.00 N/m
Performance	Fiberglass	28.98 oz/in		317.32 N/m
	Phenolic	29.97 oz/in		328.17 N/m
	Nylon	40.55 oz/in		444.01 N/m
	(Adhesive performance after a 72 hour dwell)			
Service Temperatures	1-40 minutes	572°F		300°C
	2-4 minutes	617°F		325°C
	1-9 seconds	842°F		450°C
	1-3 seconds	1000°F		538°C
Application Temp.	Minimum	50°F		10°C
Chemical Resistance	Test should be conducted at consist of five cycles of 10 m followed by 30 minute recov	ninute imm	ersions in the specif s. Cotton swab rub	ied chemical reagent
	Household Cleaners Mild Acid Oil Water 1 Part IPA, 1 Part Mineral Terpene Defluxer Toluene Saponifier	Spirits	No effect No effect No effect No effect No effect No effect No effect	
Storage Stability	Mild Acid Oil Water 1 Part IPA, 1 Part Mineral Terpene Defluxer Toluene	t 70 degree	No effect No effect No effect No effect No effect No effect No effect ses F (21 degrees C) a	

